

STRUCTURE: Silicon monolithic integrated circuits

PRODUCT: Stereo Class-D Power Amplifier For Speaker

BD5431EFS TYPE: PACKAGE: HTSSOP-A44

FEATURES:

- 1) Differential Analog / PWM inputs
- 2) High efficiency and low heat generation eliminates external heat-sinks
- Eliminates pop noise generated when the power supply goes on/off, or when the power supply is suddenly shut off
- 4) High quality muting performance is realized by using the soft-switching technology
- Incorporates a master/slave function that enables synchronous operation when several units are used simultaneously
- Allows the internal PWM sampling clock frequency to be adjusted

OAbsolute maximum ratings (Ta=25°C)

I tem	Symbol	Limit	Unit	Conditions
Supply voltage	Vcc	+20	٧	Pin7、8、15、16、29、30、37、38、40 ※1 ※2
D 1: 1:	Pd	2.0	W	※ 3
Power dissipation		4.5	W	※ 4
Input voltage for signal pin	V_{IN}	-0.2 ∼ +7.2	V	Pin1, 2, 3, 4 ※1
Input voltage for control pin	V_{CONT}	-0.2 ~ Vcc+0.2	٧	Pin20、24 ※1
Input voltage for clock pin	V _{osc}	-0.2 ∼ +7.2	٧	Pin23 ※1
Operating temperature range	Topr	−40 ~ +85	°C	
Storage temperature range	Tstg	−55 ~ +150	°C	
Maximum junction temperature	Tjmax	+150	°C	

*1 The voltage that can be applied, based on GND(Pin11, 12, 33, 34, 43)
*2 Do not, however exceed Pd and Tjmax=150°C.
*3 70mm × 70mm × 1.6mm, FR4, 1-layer glass epoxy board (Copper on bottom layer 0%)
Derating in done at 16mW/°C for operating above Ta=25°C. There are thermal vias on the board.

OOperating conditions (Ta=25°C)

Item	Symbol	Limit	Unit	Conditions
Supply voltage	Vcc	+10 ~ +16.5	٧	Pin7、8、15、16、29、30、37、38、40 ※1
Load impedance	R_L	4 ~ 16	Ω	※ 5

Do not, however exceed Pd. No radiation-proof design

⁷⁰mm × 70mm × 1.6mm, FR4, 2-layer glass epoxy board (Copper on bottom layer 100%)
Derating in done at 36mW/°C for operating above Ta=25°C. There are thermal vias on the board.



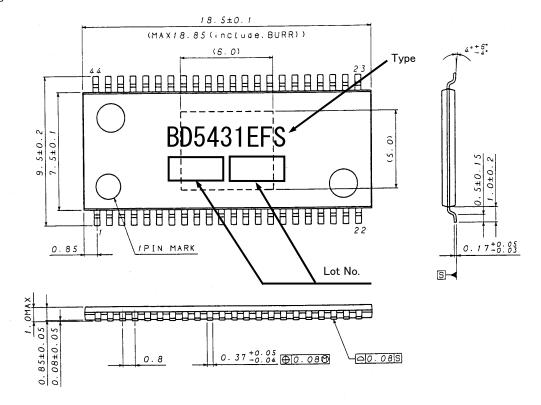
OElectrical characteristics

(Unless otherwise specified Ta=25°C, Vcc=12V, f=1kHz differential analog input、 Rg=0 Ω , R_L=8 Ω , MUTEX=H, MS=L)

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Item	Symbol	Limit		Unit	Conditions	
item		Min	Тур	Max	Offic	Conditions
Whole circuit						
Circuit current 1 (Sampling mode)	I_{CC1}	_	25	50	mA	
Circuit current 2 (Mute mode)	I_{CC2}	-	10	20	mA	MUTEX=L
Control circuit						
H level input voltage	V_{IH}	2.3	-	12	V	MUTEX, MS
L level input voltage	$V_{\rm IL}$	0	_	0.8	V	MUTEX, MS
Audio circuit						
Voltage gain	Gv	22	23.5	25	dB	Po=1W, 20log(Vout/Vin)
Maximum output power 1	P _{o1}	-	10	-	W	$R_L=8\Omega$, THD+n=10% \times 1
Maximum output power 2	P _{o2}	-	17	-	W	R _L =4Ω, THD+n=10% ※1
Total harmonic distortion	THD	_	0.1	-	%	P _o =1W, BW=20Hz ~20kHz ※1
Crosstalk	CT	60	75	-	dB	P_0 =1W, Rg=0 Ω , BW=IHF-A
Output noise voltage (Sampling mode)	V_{NO}	-	60	160	μ Vrms	$Rg=0\Omega$, BW=IHF-A
Residual noise voltage (Mute mode)	V_{NOM}	_	1	10	μ Vrms	MUTEX=L, $Rg=0\Omega$, BW=IHF-A
Internal sampling clock frequency	F _{osc}	180	250	320	kHz	

X1 These items show the typical performance of device and depend on board layout, parts, power supply.
The standard value is in mounting device and parts on surface of ROHM's board directly.

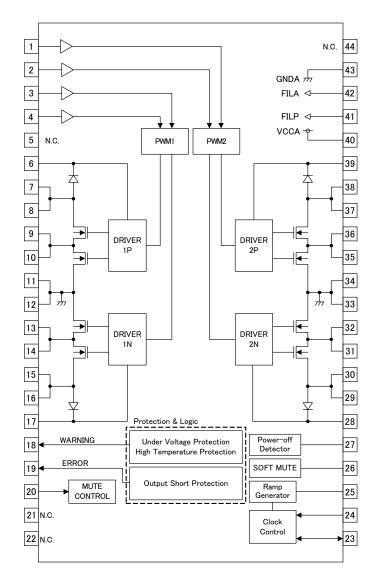
OPackage outline



(UNIT: mm) PKG: HTSSOP-A44 Drawing No.: EX195-5002



OBlock diagram



OPin No. / Pin name

Pin No.	Pin name	Pin No.	Pin name
1	IN2N	44	N.C.
2	IN2P	43	GNDA
3	IN1N	42	FILA
4	IN1P	41	FILP
5	N.C.	40	VCCA
6	BSP1P	39	BSP2P
7	VCCP1P	38	VCCP2P
8	VCCPTP	37	VUUPZP
9	OUT1P	36	OUT2P
10	OUTIP	35	OUTZP
11	GNDP1	34	GNDP2
12	GNDP1	33	GNDPZ
13	OUT1N	32	OUT2N
14	OUTIN	31	OUTZN
15	VCCP1N	30	VCCP2N
16	VOOPTIN	29	VOUPZN
17	BSP1N	28	BSP2N
18	WARNING	27	VHOLD
19	ERROR	26	TM
20	MUTEX	25	ROSC
21	N.C.	24	MS
22	N.C.	23	osc

N.C.: Non Connection.



OOperation Notes

(1) Absolute maximum ratings

Use of the IC in excess of absolute maximum ratings such as the applied voltage or operating temperature range may result in IC damage. Assumptions should not be made regarding the state of the IC (short mode or open mode) when such damage is suffered. A physical safety measure such as a fuse should be implemented when use of the IC in a special mode where the absolute maximum ratings may be exceeded is anticipated.

(2) Power supply lines

As return of current regenerated by back EMF of output coil happens, take steps such as putting capacitor between power supply and GND as a electric pathway for the regenerated current. Be sure that there is no problem with each property such as emptied capacity at lower temperature regarding electrolytic capacitor to decide capacity value. If the connected power supply does not have sufficient current absorption capacity, regenerative current will cause the voltage on the power supply line to rise, which combined with the product and its peripheral circuitry may exceed the absolute maximum ratings. It is recommended to implement a physical safety measure such as the insertion of a voltage clamp diode between the power supply and GND pins.

(3) GND potential

Ensure a minimum GND pin potential in all operating conditions.

(4) Setting of heat

Use a thermal design that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions. This IC exposes its frame of the backside of package. Note that this part is assumed to use after providing heat dissipation treatment to improve heat dissipation efficiency. Try to occupy as wide as possible with heat dissipation pattern not only on the board surface but also the backside.

Class-D power amplifier is High efficiency and low heat generation by comparison with conventional Analog power amplifier. However, In case it is operated continuously by maximum output power, Power dissipation(Pdiss) may exceed package dissipation. Please consider about heat design that Power dissipation(Pdiss) does not exceed Package dissipation(Pd) in average power(Poav). (Tjmax: Maximum junction temperature=150°C, Ta: Peripheral temperature[°C], θ ja: Thermal resistance of package[°C/W], Poav: Average power[W], η : Efficiency)

Package dissipation: Pd (W) = $(Tjmax - Ta) / \theta ja$ Power dissipation: Pd iss $(W) = Poav * (1 / \eta - 1)$

(5) Actions in strong magnetic field

Use caution when using the IC in the presence of a strong magnetic field as doing so may cause the IC to malfunction.

(6) Thermal shutdown circuit

This product is provided with a built-in thermal shutdown circuit. When the thermal shoutdown circuit operates, the output transistors are placed under open status. The thermal shutdown circuit is primarily intended to shut down the IC avoiding thermal runaway under abnormal conditions with a chip temperature exceeding Tjmax = 150° C, and is not intended to protect and secure an electrical appliance.

(7) Shorts between pins and misinstallation

When mounting the LSI on a board, pay adequate attention to orientation and placement discrepancies of the LSI. If it is misinstalled and the power is turned on, the LSI may be damaged. It also may be damaged if it is shorted by a foreign substance coming between pins of the LSI or between a pin and a power supply or a pin and a GND.

(8) Power supply on/off

In case power supply is started up, MUTEX (Pin20) always should be set LOW, And in case power supply is shut down, it should be set LOW likewise. Then it is possible to eliminate pop noise when power supply is turned on/off. And also, all power supply terminals should start up and shut down together.

(9) WARNING terminal(Pin18), ERROR terminal(Pin19)

A WARNING flag is outputted when Under Voltage Protection and High Temperature Protection are operated. A Error flag is outputted when Output Short Protection and Output DC Voltage Protection are operated. These flags are the function which the condition of this product is shown in. The use which aimed at the protection except for this product is prohibition.

(10) N.C. terminal(Pin5, 21, 22, 44)

N.C. terminal(Non Connection Pin) does not connect to the inside circuit. Therefore, please open or connect to GND.

Notes

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